

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOUNG JAE LEE	12/27/2016
JI SUN LEE	12/27/2016
HO JAE LEE	12/27/2016
RECEIVING PARTY DATA	
Name:	KJ TECHNOLOGY CO., LTD.
Street Address:	GEOMAM-DONG, ROYAL PLAZA
Internal Address:	104HO, 587, SEUNGHAK-RO, SEO-GU
City:	INCHEON
State/Country:	KOREA, REPUBLIC OF
Name:	JCTECH CO., LTD.
Street Address:	115B 7L GOJAN-DONG 125, 557 BEON-GIL
Internal Address:	NEUNGHEODAE-RO, NAMDONG-GU
City:	INCHEON
State/Country:	KOREA, REPUBLIC OF
Postal Code:	21699
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15374797
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NAME OF SUBMITTER:	DOUGLAS W. SWARTZ
SIGNATURE:	/Douglas W. Swartz/
DATE SIGNED:	01/04/2017
Total Attachments: 2 source=Assignment-15374797#page1.tif source=Assignment-15374797#page2.tif	

Worldwide Assignment

WHEREAS, I/We **Young Jae LEE, Ji Sun LEE and Ho Jae LEE**, have made an invention entitled "**A HEAT-RESISTANT RECEPTACLE CAP**" for which I/We have prepared an application for Letters Patent of the United States, or filed an application for Letters Patent of the United States on December 09, 2016, under Application No. 15/374,797; and

WHEREAS, **KJ TECHNOLOGY CO., LTD.** ("ASSIGNEE"), a corporation or other business entity duly registered in the State/Country of **Republic of Korea**, whose address is **(Geomam-dong, Royal Plaza) 104Ho, 587, Seunghak-ro, Seo-gu Incheon**, desires to acquire the entire right, title, and interest in and to the invention, the application, and any Letters Patent to be granted for the invention in the United States and in all foreign countries; and

WHEREAS, **JCTECH CO., LTD.** ("ASSIGNEE"), a corporation or other business entity duly registered in the State/Country of **Republic of Korea**, whose address is **115B 7L (Gojan-dong) 125, 557 Beon-gil, Neungheodaero, Namdong-gu, Incheon 21699**, desires to acquire the entire right, title, and interest in and to the invention, the application, and any Letters Patent to be granted for the invention in the United States and in all foreign countries;

NOW, THEREFORE, in view of good and valuable consideration, paid to me/us by ASSIGNEE, the receipt and sufficiency of which I/We acknowledge, I/We, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest in and to the invention, the application, all applications claiming benefit of the application, including, but not limited to, all divisions and continuation of the application, and all Letters Patent that may be granted thereon in the United States, and in all foreign countries, and all reissues thereof, together with the right to claim priority under the International Convention in all member countries; and I/We authorize and request the Director of Patents and Trademarks to issue all Letters Patent for the invention to ASSIGNEE, its successors, legal representatives, and assigns in accordance with the terms of this Assignment.

AND I/We covenant and agree that I/We have the full right to convey the entire right, title, and interest herein assigned and that I/We have not executed and will not execute any assignment or other instrument in conflict with this Assignment.

AND I/We further covenant and agree that upon request by ASSIGNEE, its successors, legal representatives, and/or assigns, and without further consideration, I/We will do all lawful acts that may be necessary or desirable to assist ASSIGNEE, its successors, legal representatives, and/or assigns to obtain and enforce patent protection for the invention in the United States and in all foreign countries, including, but not limited to, communicate with ASSIGNEE, its successors, legal representatives, and/or assigns any facts known to me/us regarding the invention, testify in any legal proceeding, sign all lawful papers, execute and deliver all papers that may be necessary or desirable to perfect the title to the invention in ASSIGNEE, its successors, legal representatives, and/or assigns, execute all divisional, continuation, and reissue applications, and make all rightful oaths, it being understood that any expense incident to the rendering of such assistance will be borne by ASSIGNEE, its successors, legal representatives, and/or assigns;

AND I/We further hereby authorize ASSIGNEE, or its attorneys or agents, to insert the correct Application Number and filing Date into this Assignment, if none is indicated on that date of my/our execution of this agreement.

IN WITNESS WHEREOF, I/We have executed this Assignment on the date(s) indicated below.

Signature: Young Jae LEE

Date: Dec. 27, 2016

Full Name: Young Jae LEE

Address: (Yeouido-dong Gwangjang Apt.) 1-807, 12, Yeouinaru-ro, Yeongdeungpo-gu, Seoul,
Republic of Korea

Signature: Ji Sun LEE

Date: Dec. 27, 2016

Full Name: Ji Sun LEE

Address: (Sang-dong, Sarang Masul Apt.) 1612-2101, 150, Buheung-ro, Wonmi-gu, Bucheon-si,
Gyeonggi-do 14600, Republic of Korea

Signature: No Jae LEE

Date: Dec. 27, 2016

Full Name: No Jae LEE

Address: (Sang-dong, Sarang Maeul Apt.) 1612-2101, 150, Buheung-ro, Wonmi-gu, Bucheon-si,
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